

PCN Number:	20160407001	PCN Date:	04/18/2016
Title:	Datasheet for TPS61040-Q1/TPS61041-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:	<input type="checkbox"/> Assembly Site <input type="checkbox"/> Design <input type="checkbox"/> Wafer Bump Site <input type="checkbox"/> Assembly Process <input checked="" type="checkbox"/> Data Sheet <input type="checkbox"/> Wafer Bump Material <input type="checkbox"/> Assembly Materials <input type="checkbox"/> Part number change <input type="checkbox"/> Wafer Bump Process <input type="checkbox"/> Mechanical Specification <input type="checkbox"/> Test Site <input type="checkbox"/> Wafer Fab Site <input type="checkbox"/> Packing/Shipping/Labeling <input type="checkbox"/> Test Process <input type="checkbox"/> Wafer Fab Materials <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> Wafer Fab Process		

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below:



TPS61040-Q1, TPS61041-Q1

SGLS276D – JANUARY 2005 – REVISED MARCH 2016

www.ti.com

Changes from Revision C (April 2012) to Revision D	Page
• Changed bullets in <i>Applications</i>	1
• Added <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Changed TPS61040/TPS61041 to TPS6104x-Q1, add -Q1 to TPS61040 and TPS61041, VIN and Vin to V _{IN} , C _{FF} to C _{FF} , R _{DS(ON)} and R _{DS(on)} to R _{DS(on)} , and I _{sw} to I _{SW} throughout document	1
• Updated text in <i>Description</i>	1
• Added MAX value of 47 in the Inductor row of <i>Recommended Operating Conditions</i> for better clarity	4
• Changed Operating junction temperature row to Operating ambient temperature row in <i>Recommended Operating Conditions</i>	4
• Changed T _J to T _A in the conditions statement of <i>Electrical Characteristics</i>	5
• Moved figures 12 through 14 to <i>Application Curves</i> section	6
• Deleted 50 mA from <i>Inductor Selection, Maximum Load Current</i>	11
• Deleted Sumida CR32-100 row from <i>Table 3</i>	13
• Changed Layout Diagram in <i>Layout Example</i>	19

Device Family	Change From:	Change To:
TPS61040-Q1/TPS61041-Q1	SGLS276C	SGLS276D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/tps61040-q1>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TPS61040QDBVRQ1	TPS61041QDBVRQ1
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com